IEEE, CPMT, IMAPS, iNEMI and SEMI Global Interposer Technology (GIT) 2011 Workshop

November 14-15, 2011 • Georgia Tech • Atlanta GA • USA

TECHNICAL COMMITTEES

Rao Tummala Phil Garrou

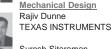
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Nagesh Vodrahalli ALTERA



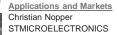
Venky Sundaram GEORGIA TECH



NiteshKumbhat GEORGIA TECH



William Chen



Jerome Baron YOLE

Manufacturing Infrastructure Thorsten Mattius **EV GROUP**

Tom Salmon SEMI

Student Poster Session Saumya Gandhi **GEORGIA TECH**

Vijay Sukumaran **GEORGIA TECH**

GIT 2011 OVERVIEW

The GIT 2011 Workshop is intended to compare and contrast the wide variety of interposer approaches being developed as well as promote and disseminate revolutionary and evolutionary advances in emerging silicon, glass and other interposer technologies, by bringing together academic and industry researchers, technology developers, users and manufacturers from around the world. Such a technology is seen as not only for packaging of ICs and 3D ICs but also act as a better alternative to 3D ICs with TSV, and eventually providing a path for entire systems.

The first of its kind, the GIT 2011 Workshop will bring together industry experts, global academic researchers, and student leaders to share leading-edge interposer technology research, development, applications, markets and manufacturing infrastructure. It is a must-attend event for those highly interested in interposer technology advances for the future.

Technical Sessions on Interposer Technology will feature technical leaders in the following topics:

- 1. Electrical Design
- Mechanical Design
- Silicon Interposers 3.
- 4. Glass Interposers
- Chip Level Interconnections
- 6. Board Level Interconnections
- Applications and Markets
- Manufacturing Infrastructure



KEYNOTE SPEAKERS



Subramanian Iyer IBM Fellow. Chief Scientist IBM



Jerome Baron Market & Technology Analyst YOLÉ



Rao R. Tummala Director, Packaging Research Center **GEORGIA TECH**

REGISTRATION

Workshop Registration includes access to all technical sessions and includes all meals. Registration Fees - EARLY Registration ends October 15, 2011. Register early - space is limited. Sponsoring Society Non-Member \$400 Committee, Advisor or Speaker \$250 Sponsoring Society Member \$300 Student \$100

www.prc.gatech.edu/git2011/registration.html

CALL FOR PAPERS – TITLES for PRESENTATIONS AND POSTERS

Submit TITLE for Technical Sessions listed above.

- Oral presentations will be made by Industry, Academic, and Research Faculty
- Posters will be presented by Students

Deadline for TITLE submission is October 2, 2011. Notification of acceptance by October 15, 2011.

www.prc.gatech.edu/git2011/papers.html

HOTEL ACCOMMODATIONS

Discount GIT 2011 Hotel Rates:

Georgia Tech Hotel and Conference Center - US\$125 Marriott Renaissance Atlanta Midtown – US\$144

Register early – space is limited.

www.prc.gatech.edu/git2011/travel.html

INDUSTRY AND ACADEMIC ADVISORS

Altera - Tarun Verma Amkor - Robert Darveaux DNP - Atsushi Takano Dow - Leo Linehan Flextronics - Dongkai Shangguan Ibiden - Takashi Kariva IBM - Subramanian İyer Intel - Bob Sankman Nvidia - Joe Grecco

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